

Bill of Materials

TI DESIGNS TIDA00593

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	7	C1, C2, C4, C5, C7, C11, C12	0.1uF	CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	MuRata	GRM155R61A104KA01D		0402	
2	2	C3, C6	0.47uF	CAP, CERM, 0.47 µF, 6.3 V, +/- 10%, X5R, 0402	MuRata	GRM155R60J474KE19D		0402	
3	3	C8, C9, C10	150pF	CAP, CERM, 150 pF, 50 V, +/- 5%, C0G/NP0, 0402	MuRata	GRM1555C1H151JA01D		0402	
4	2	J1, J2		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	On-Shore Technology	ED555/2DS		7.0x8.2x6.5mm	
5	2	J3, J4		Header (friction lock), 100mil, 4x1, R/A, TH	Molex	22-05-3041		4x1 R/A Header	
6	2	J5, J6		Header, 100mil, 2x1, Tin, TH	Sullins Connector Solu	PEC02SAAN		Header, 2 PIN, 100mil, Tin	
7	1	R1	0.01	RES, 0.01, 1%, 1 W, 1206	Vishay-Dale	WSLP1206R0100FEA		1206	
8	2	R2, R14	10k	RES, 10 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW040210K0JNED		0402	
9	5	R3, R4, R11, R12, R13	100	RES, 100, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402100RJNED		0402	
10	3	R5, R6, R7	300	RES, 300, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402300RJNED		0402	
11	3	R8, R9, R10	1.00Meg	RES, 1.00 M, 1%, 0.063 W, 0402	Vishay-Dale	CRCW04021M00FKED		0402	
12	1	RT1	10.0k ohm	Thermistor NTC, 10.0k ohm, 1%, Disc, 5x8.4 mm	SEMITEC Corporation	103AT-2		Disc, 5x8.4 mm	
13	9	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9	Black	Test Point, Miniature, Black, TH	Keystone	5001		Black Miniature Testpoint	
14	1	U1		Single Cell Li-Ion Battery Fuel Gauge for Battery Pack Integration, DRZ0012A	Texas Instruments	BQ27542DRZR-G1	BQ27542DRZT-G1	DRZ0012A	

Notes:

Unless otherwise noted in the Alternate Part column, all parts may be substituted with equivalents.

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